



## Description

### JMT N And P-Channel Enhancement Mode MOSFET

#### Features

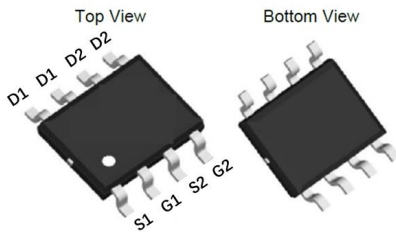
- N-Channel: 30V, 10A  
 $R_{DS(ON)} < 13m\Omega @ V_{GS} = 10V$   
 $R_{DS(ON)} < 20m\Omega @ V_{GS} = 4.5V$
- P-Channel: -30V, -12A  
 $R_{DS(ON)} < 25m\Omega @ V_{GS} = -10V$   
 $R_{DS(ON)} < 35m\Omega @ V_{GS} = -4.5V$
- Excellent Gate Charge x  $R_{DS(ON)}$  Product(FOM)
- Very Low On-resistance  $R_{DS(ON)}$
- Fast Switching Speed

#### Application

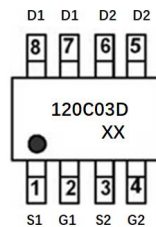
- Battery Protection
- Load Switch
- Power Management



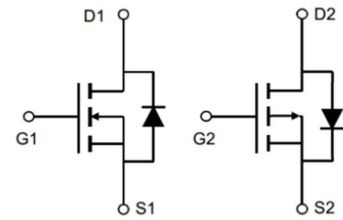
**100% UIS TESTED!**  
**100% ΔVds TESTED!**



SOP-8(Dual)



Marking and pin Assignment



Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
120C03D	JMTP120C03D	TAPING	SOP-8	13inch	4000	48000

## Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise specified)

Symbol	Parameter	Max. N-Channel	Max. P-Channel	Units
V <sub>DSS</sub>	Drain-Source Voltage	30	-30	V
V <sub>GSS</sub>	Gate-Source Voltage	±20	±20	V
I <sub>D</sub>	Continuous Drain Current	T <sub>A</sub> = 25°C	-12	A
		T <sub>A</sub> = 100°C	-7.8	A
I <sub>DM</sub>	Pulsed Drain Current <sup>note1</sup>	40	-48	A
E <sub>AS</sub>	Single Pulsed Avalanche Energy <sup>note2</sup>	17	24	mJ
P <sub>D</sub>	Power Dissipation	2.2	6.1	W
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient	57	20	°C/W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to +150		°C



## N-Channel Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V	-	-	1.0	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1.0	1.4	2.5	V
R <sub>DS(on)</sub>	Static Drain-Source on-Resistance <small>note3</small>	V <sub>GS</sub> =10V, I <sub>D</sub> =10A	-	10	13	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A	-	15	20	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1.0MHz	-	584	-	pF
C <sub>oss</sub>	Output Capacitance		-	112	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	96	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =15V, I <sub>D</sub> =10A, V <sub>GS</sub> =10V	-	15	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	4.7	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		-	3.6	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =30V, I <sub>D</sub> = 20A, R <sub>REN</sub> =3Ω, V <sub>GS</sub> =10V	-	5	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	8	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	21	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	7	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	10	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	40	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> = 10A	-	-	1.2	V
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =20A, dI/dt=100A/μs	-	7	-	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery		-	5.9	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : T<sub>J</sub>=25°C, V<sub>DD</sub>=15V, V<sub>G</sub>=10V, L=0.5mH, R<sub>g</sub>=25Ω, I<sub>AS</sub>=8.3A

T<sub>J</sub>=25°C, V<sub>DD</sub>=-15V, V<sub>G</sub>= -10V, L=0.5mH, R<sub>g</sub>=25Ω, I<sub>AS</sub>= -9.8A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%



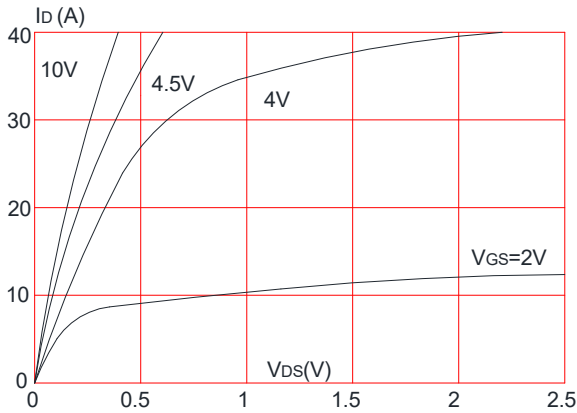
## P-Channel Electrical Characteristics (T<sub>J</sub>=25°C unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> = -250μA	-30	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -30V, V <sub>GS</sub> =0V	-	-	-1	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1.0	-1.5	-2.5	V
R <sub>DS(on)</sub>	Static Drain-Source on-Resistance <small>note3</small>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -10A	-	19	25	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -5A	-	27	35	
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = -15V, V <sub>GS</sub> =0V, f=1.0MHz	-	1200	-	pF
C <sub>oss</sub>	Output Capacitance		-	155	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	139	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = -15V, I <sub>D</sub> = -8A, V <sub>GS</sub> = -10V	-	52	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	9.8	-	nC
Q <sub>gd</sub>	Gate-Drain("Miller") Charge		-	8.3	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> = -15V, I <sub>D</sub> = -1A, V <sub>GS</sub> = -10V, R <sub>GEN</sub> =6Ω R <sub>D</sub> =15Ω	-	13	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	15	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	198	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	98	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	-12	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-48	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> = -12A	-	-	-1.2	V
trr	Reverse Recovery Time	T <sub>J</sub> =25°C,	-	37	-	ns
Qrr	Reverse Recovery Charge	I <sub>F</sub> =-2A, dI/dt=-100A/μs	-	36	-	nC

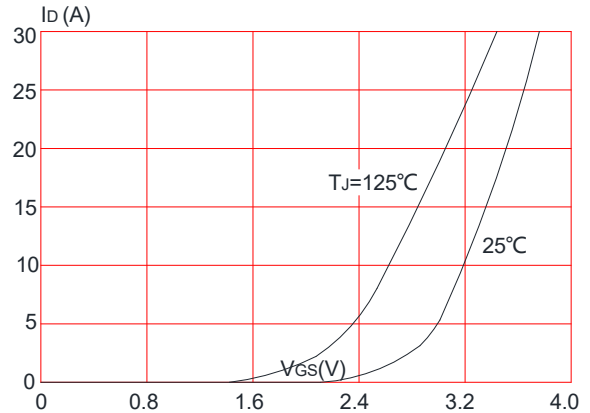


## Typical Performance Characteristics-N

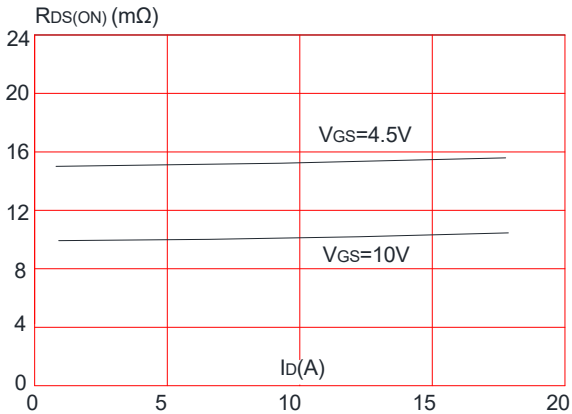
**Figure 1: Output Characteristics**



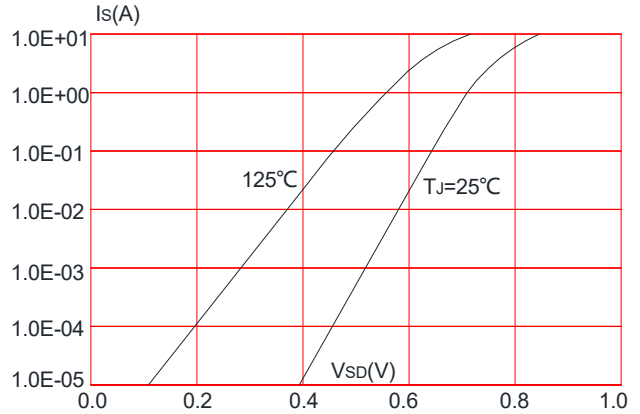
**Figure 2: Typical Transfer Characteristics**



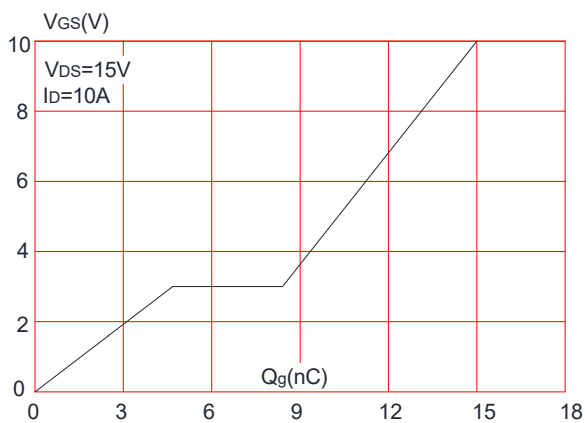
**Figure 3: On-resistance vs. Drain Current**



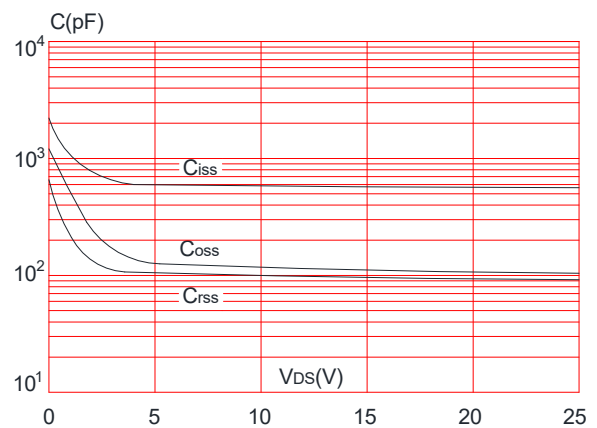
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**

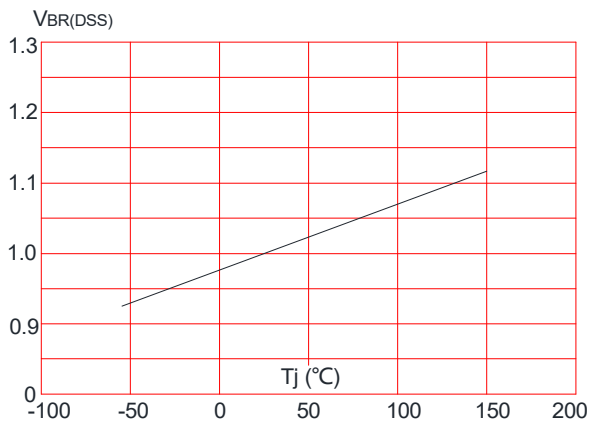


**Figure 6: Capacitance Characteristics**

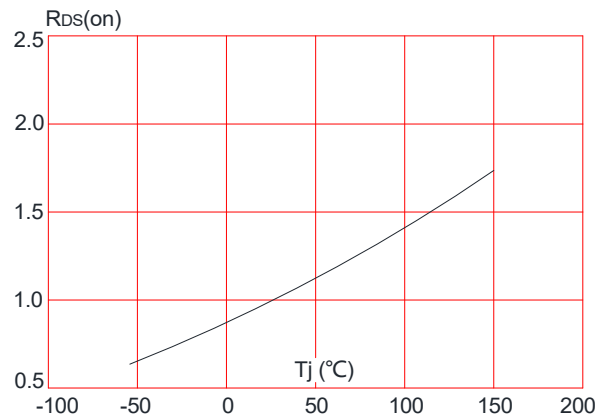




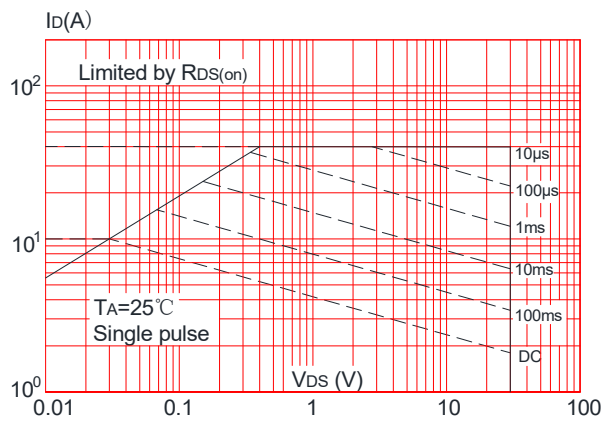
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



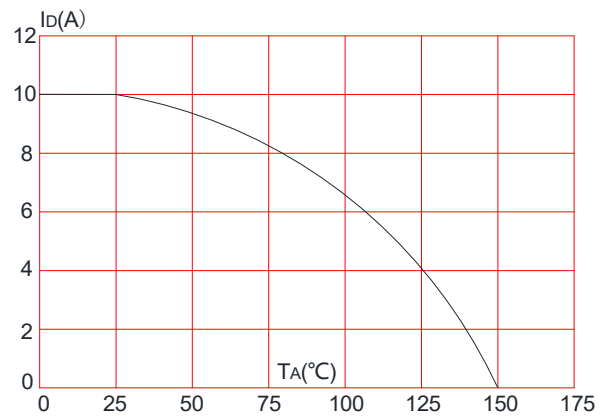
**Figure 8:** Normalized on Resistance vs. Junction Temperature



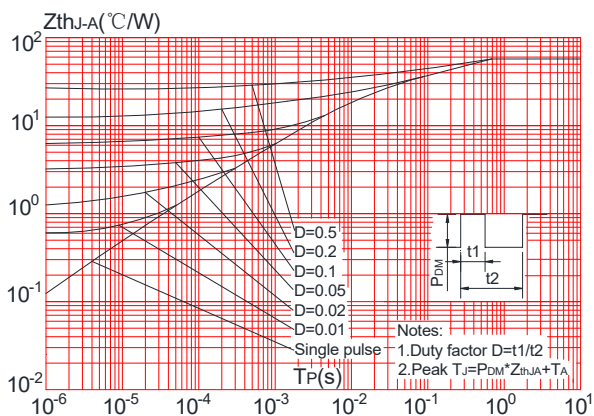
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



## Test Circuit-N

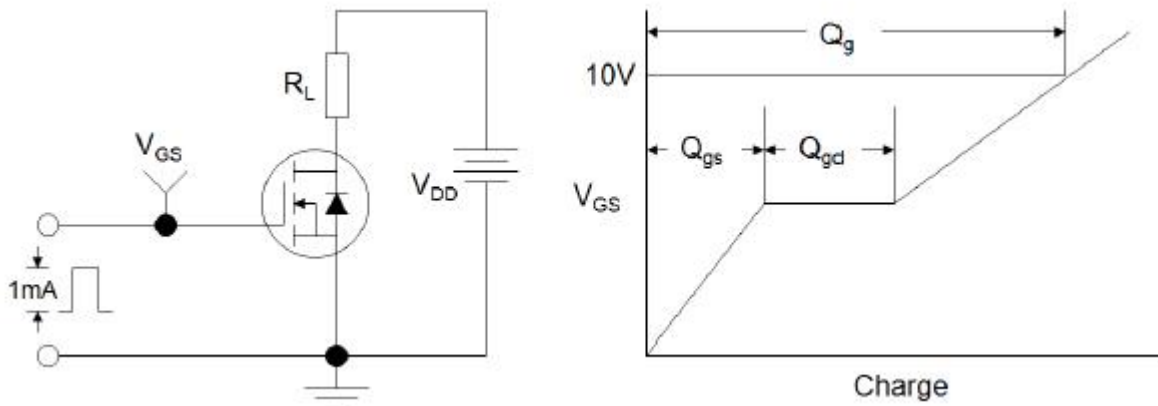


Figure1:Gate Charge Test Circuit & Waveform

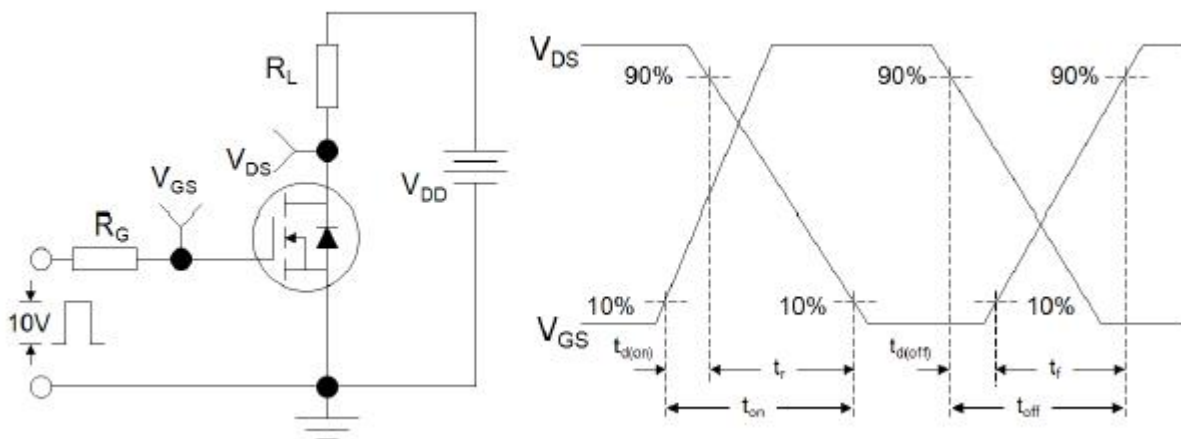


Figure 2: Resistive Switching Test Circuit & Waveforms

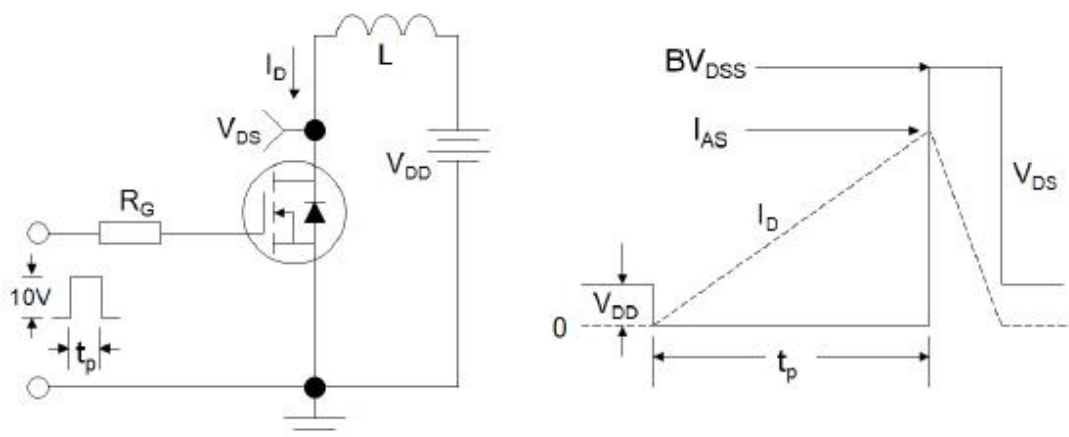
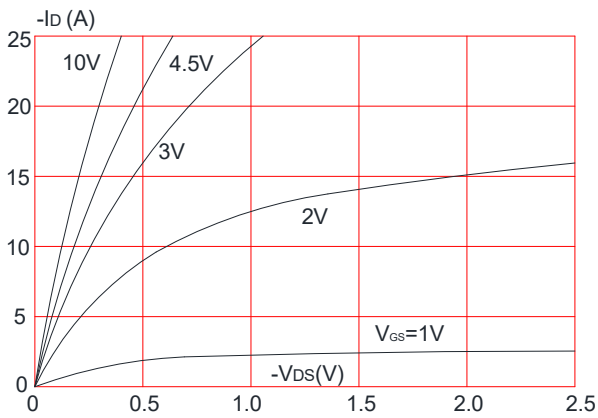


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

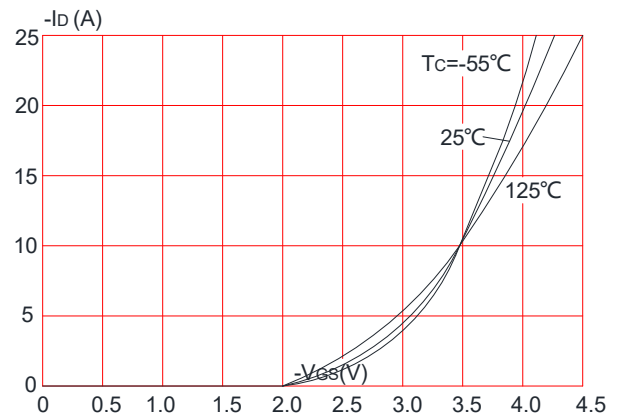


## Typical Performance Characteristics-P

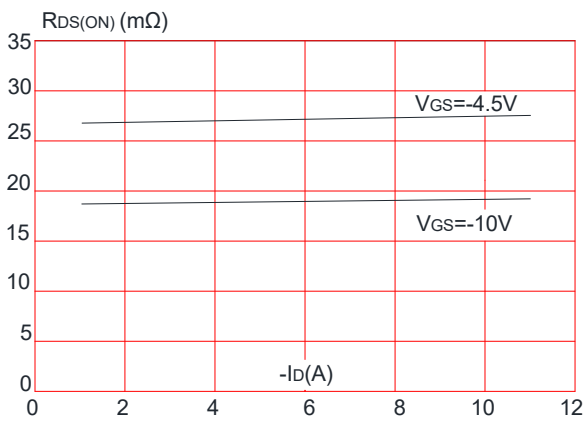
**Figure 1:** Output Characteristics



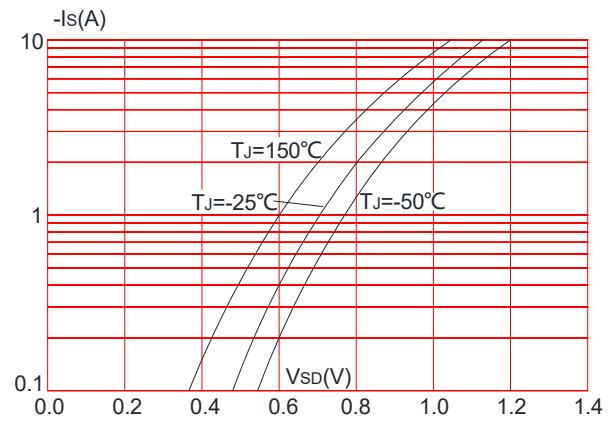
**Figure 2:** Typical Transfer Characteristics



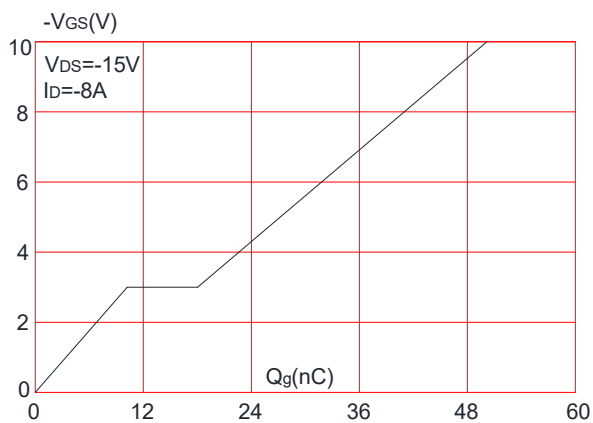
**Figure 3:** On-resistance vs. Drain Current



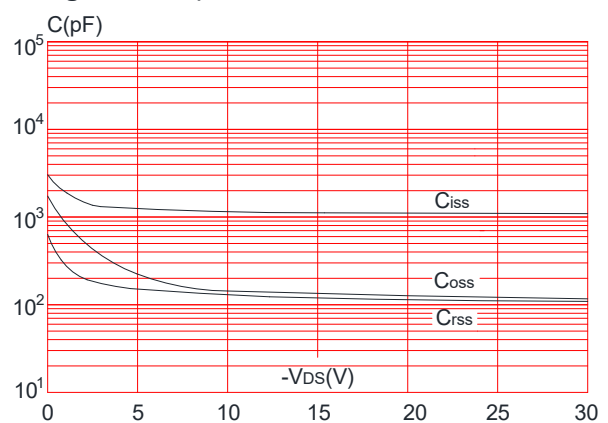
**Figure 4:** Body Diode Characteristics



**Figure 5:** Gate Charge Characteristics

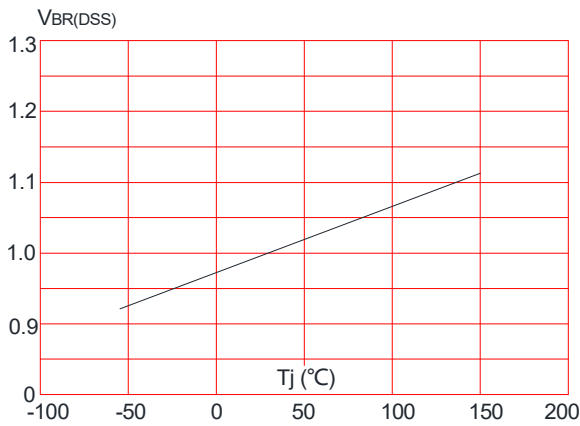


**Figure 6:** Capacitance Characteristics

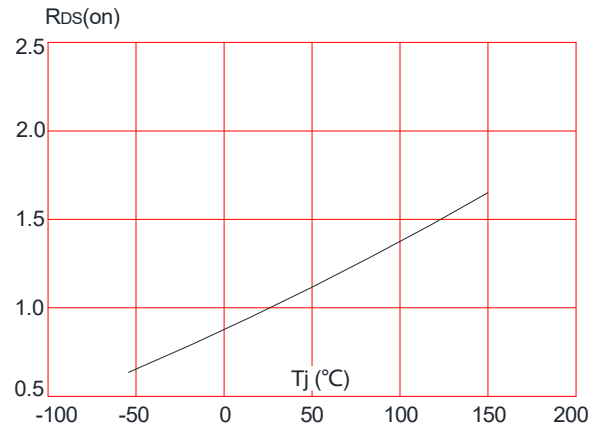




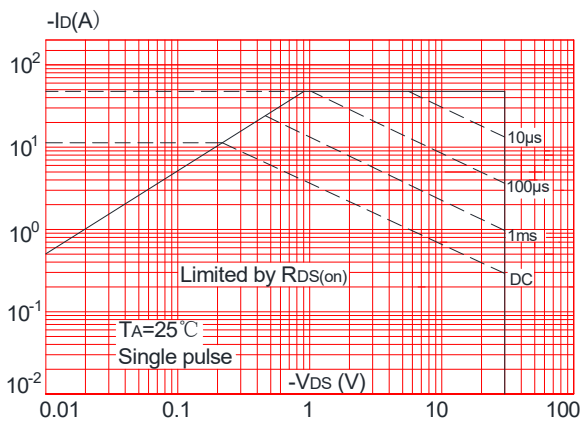
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



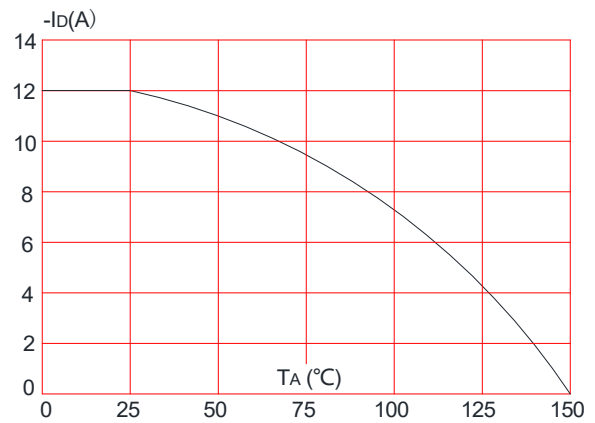
**Figure 8:** Normalized on Resistance vs. Junction Temperature



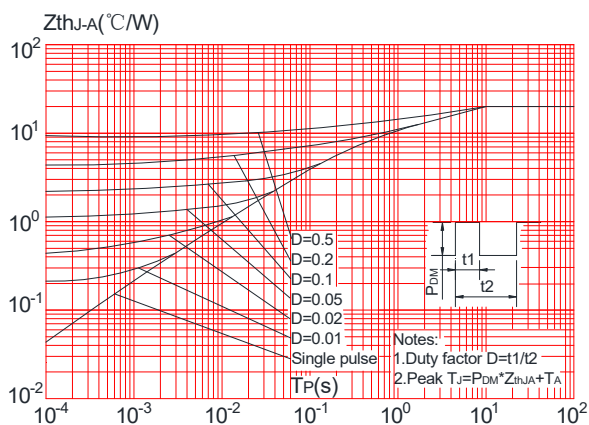
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



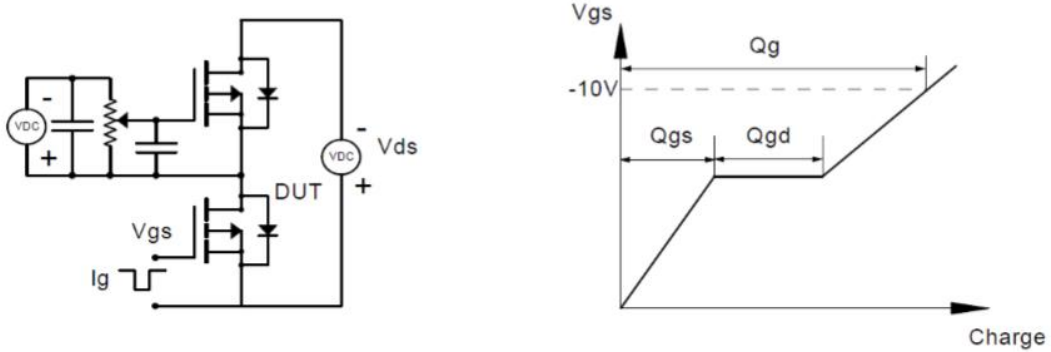
**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



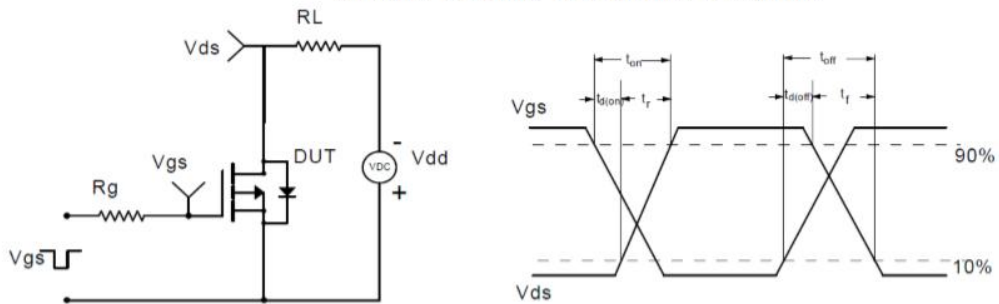


## Test Circuit-P

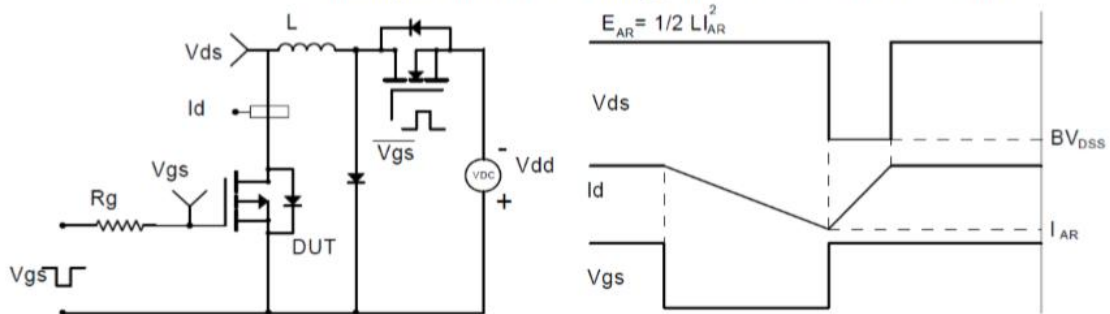
### Gate Charge Test Circuit & Waveform



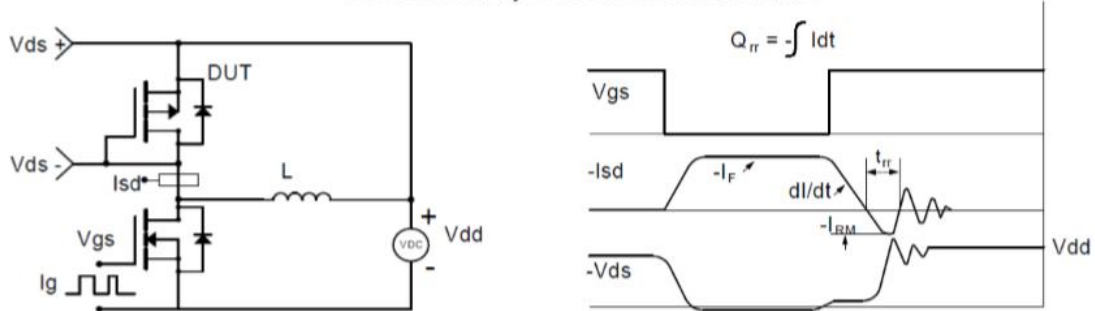
### Resistive Switching Test Circuit & Waveforms



### Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

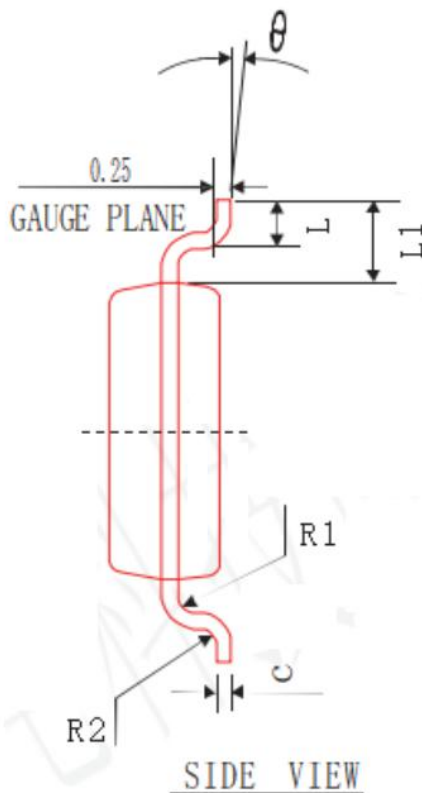
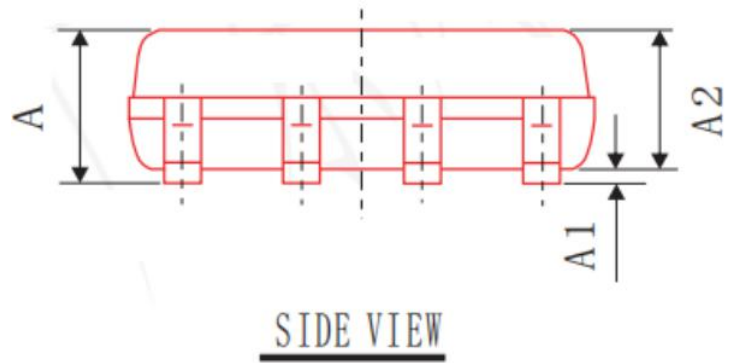
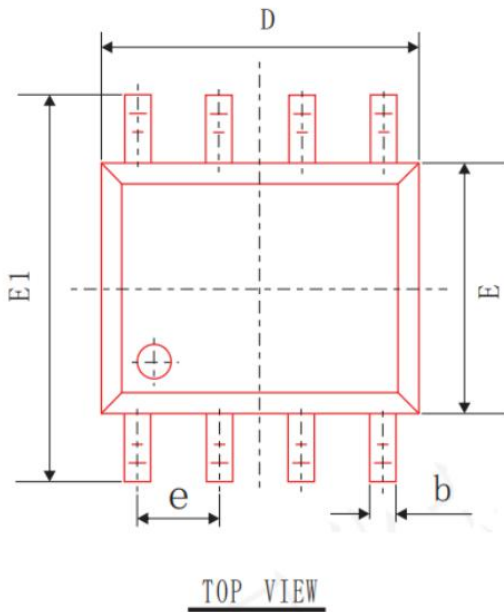


### Diode Recovery Test Circuit & Waveforms





## Package Mechanical Data-SOP-8




SYMBOL	MIN	NOM	MAX
A	1.40	1.60	1.80
A1	0.05	0.15	0.25
A2	1.35	1.45	1.55
b	0.30	0.40	0.50
c	0.153	0.203	0.253
D	4.80	4.90	5.00
E	3.80	3.90	4.00
E1	5.80	6.00	6.20
L	0.45	0.70	1.00
$\theta$	2°	4°	6°
L1	1.04 REF		
e	1.27 BSC		
R1	0.07 TYP		
R2	0.07 TYP		



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